



WINSTAR Display Co.,Ltd.
華凌光電股份有限公司

2.9 inch E-paper Display Series

WAA0290A2CNA8NXX000

Product Specifications

Customer	Standard
Description	2.9" EPAPER DISPLAY
Model Name	WAA0290A2CNA8NXXX000
Date	2024/08/19
Revision	1.0

	Design Engineering		
	Approval	Check	Design

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1. Over View

WAA0290A2CNA8NXXX000 is a reflective electrophoretic technology display module on an active matrix TFT substrate. The panel is capable of displaying black, white, yellow and red images depending on the associated lookup table used. The circuitry on the panel includes an integrated gate and source driver, timing controller, oscillator, DC-DC boost circuit, and memory to store the frame buffer and lookup tables, and additional circuitry to control VCOM and BORDER settings.

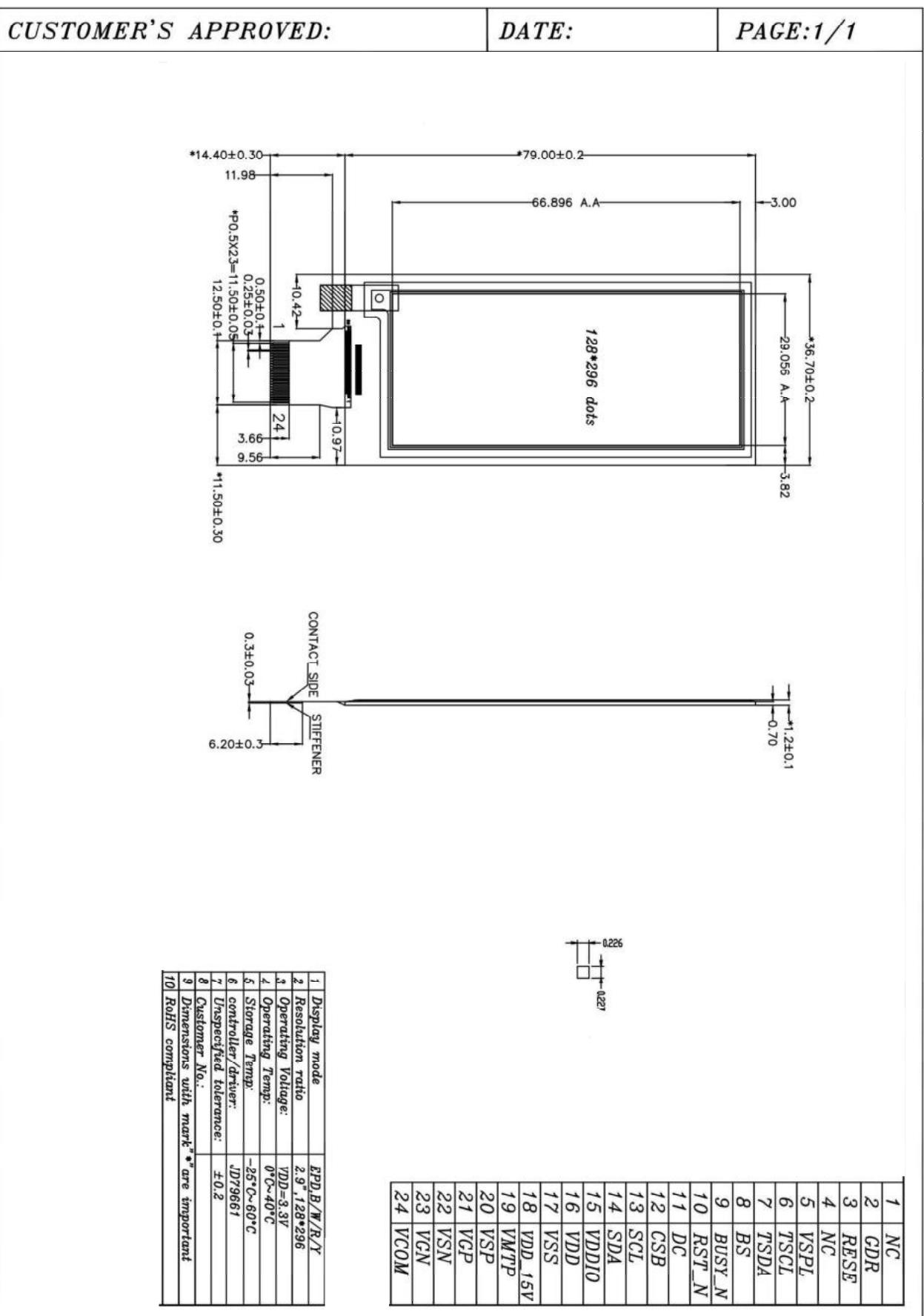
2. Features

- Highlight Red and Yellow color
- High contrast
- High reflectance
- Ultra wide viewing angle
- Ultra low power consumption
- Pure reflective mode
- Bi-stable display
- Antiglare hard-coated front-surface
- Low current deep sleep mode
- On chip display RAM
- Waveform stored in On-chip OTP
- Serial peripheral interface available
- On-chip oscillator
- On-chip booster and regulator control for generating VCOM, Gate and Source driving voltage
- I²C signal master interface to read external temperature sensor
- Available in COG package

3. Mechanical Specifications

Parameter	Specifications	Unit	Remark
Screen Size	2.9	Inch	
Display Resolution	128(H)×296(V)	Pixel	Dpi:112
Active Area	29.056×6.896	mm	
Pixel Pitch	0.226×0.227	mm	
Pixel Configuration	Rectangle		
Outline Dimension	36.7(H)×79.0(V) ×1.2(D)	mm	
Weight	5.09±0.5	g	

4. Mechanical Drawing of EPD module



5. Input /Output Pin Assignment

No.	Name	I/O	Description	Remark
1	NC		Do not connect with other NC pins	Keep Open
2	GDR	O	This pin is N-MOS gate control.	
3	RESE	P	Current sense input for control loop.	
4	NC	NC	Do not connect with other NC pins	Keep Open
5	VSPL	P	Positive source voltage	
6	TSCL	O	I ² C clock for external temperature sensor (I ² C interface need external pull high resistance.) Must pull high or low if not used.	
7	TSDA	I/O	I ² C data for external temperature sensor (I ² C interface need external pull high resistance.) Must pull high or low if not used.(Default low)	
8	BS	I	Input interface setting.	
9	BUSY_N	O	This pin indicates the driver status.	
10	RST_N	I	Global reset pin. Low reset. (normal pull high)	
11	DC	I	Serial communication Command/Data input	
12	CSB	I	Serial communication chip select.	
13	SCL	I	Serial communication clock input.	
14	SDA	I/O	Serial communication data input.	
15	VDDIO	P	IO voltage supply	
16	VDD	P	Digital/Analog power.	
17	VSS	P	Ground	
18	VDD_15V	P	1.5V voltage input &output	
19	VMTP	P	MTP program power (10.1V)	
20	VSP	P	Positive source voltage	
21	VGP	P	Positive gate voltage	
22	VSN	P	Negative Source driving voltage	
23	VGN	P	Negative gate voltage	
24	VCOM	O	VCOM driving voltage	

Note: I: Input, O: Output, P: Power, D: Dummy, S: Shorted line, M: Mark, PI: Power input, PO: Power output,I/O: Input / Output. PS: Power Setting, C: Capacitor pin.

6. Electrical Characteristics

6.1 Absolute Maximum Rating

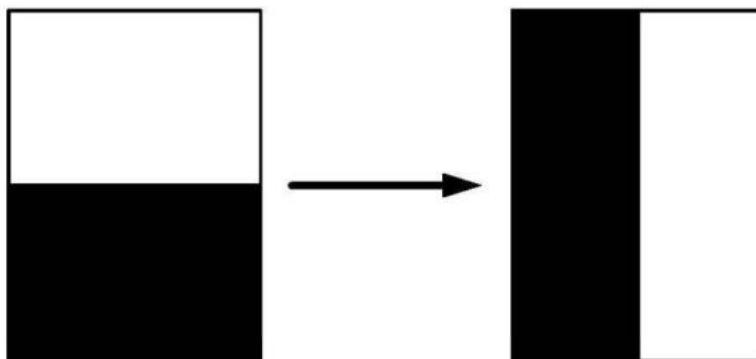
Parameter	Symbol	Rating	Unit
Logic supply voltage	VDD, AVDD,VDDIO, VDD1,VPP	-0.3 to +6.0	V
Logic Input voltage	VI	-0.3 to VDDIO+0.3	V
Operating Temp range	TOPR	0 to +40	°C
Storage Temp range	TSTG	-25 to +70	°C
Optimal Storage Humidity	HSTGo	55±10	%RH

Note: Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this data sheet is not implied. Exposing device to the absolute maximum ratings in a long period of time may degrade the device and affect its reliability.

6.2 Panel DC Characteristics

Parameter	Symbol	Conditions	Applicable pin	Min.	Typ.	Max	Units
Single ground	V _{SS}	-		-	0	-	V
Logic supply voltage	V _{IO}	-	VIO	2.3	3.3	3.6	V
Core logic voltage	V _{DD}		VDD	2.3	3.3	3.6	V
High level input voltage	V _{IH}	-	-	0.7V _{IO}	-	V _{IO}	V
Low level input voltage	V _{IL}	-	-	GND	-	0.3V _{DD}	V
High level output voltage	V _{OH}	IOH = 400uA	-	V _{IO} -0.4	-	-	V
Low level output voltage	V _{OL}	IOL = -400uA	-	GND	-	GND +0.4	V
Typical power	P _{TYP}	V _{CI} =3.3V	-	-	9.9	-	mW
Deep sleep mode	P _{STPY}	V _{CI} =3.3V	-	-	0.003	-	mW
Typical operating current	Iopr_V _{CI}	V _{CI} =3.3V	-	-	3	-	mA
Image update time	-	25 °C	-	-	25	-	sec
Stand-by current	Ist_V _{DD}		-	-	1	5	uA

Notes: 1. The typical power is measured with following transition from horizontal 2 scale pattern to vertical 2 scale pattern.



2. The deep sleep power is the consumed power when the panel controller is in deep sleep mode.
3. The listed electrical/optical characteristics are only guaranteed under the controller & waveform provided by WINSTAR Display.

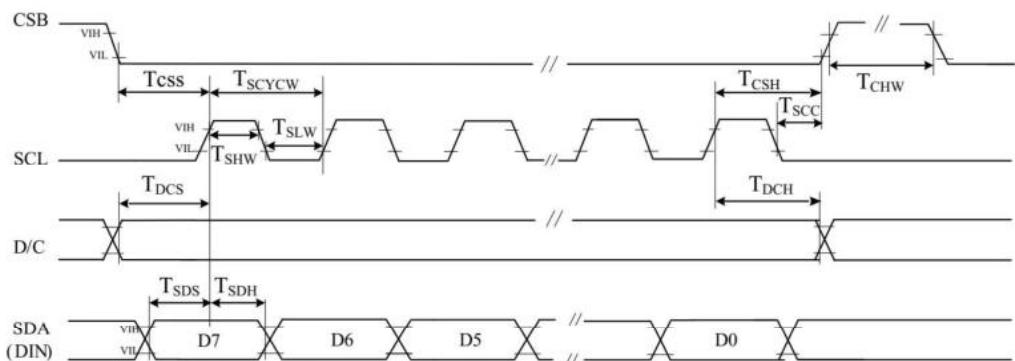
6.3 AC Characteristics

6.3.1 MCU Interface Selection

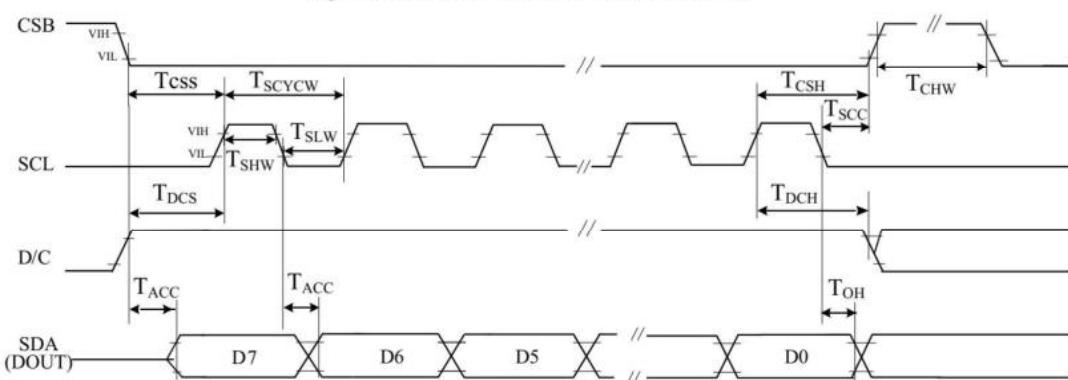
The 3-wire/4-wire serial port as communication interface for all the function and command setting. 3-wire/4-wire engine act as a “slave mode” for all the time, and will not issue any command to the 3-wire/4-wire bus itself.

Under read mode, 3-wire/4-wire engine will return the data during “Data phase”. The returned data should be latched at the rising edge of SCL by external controller. Data in the “Hi-Z phase” will be ignored by 3-wire/4-wire engine during write operation, and should be ignored during read operation also. During read operation, external controller should float SDA pin under “Hi-Z phase” and “Data phase”.

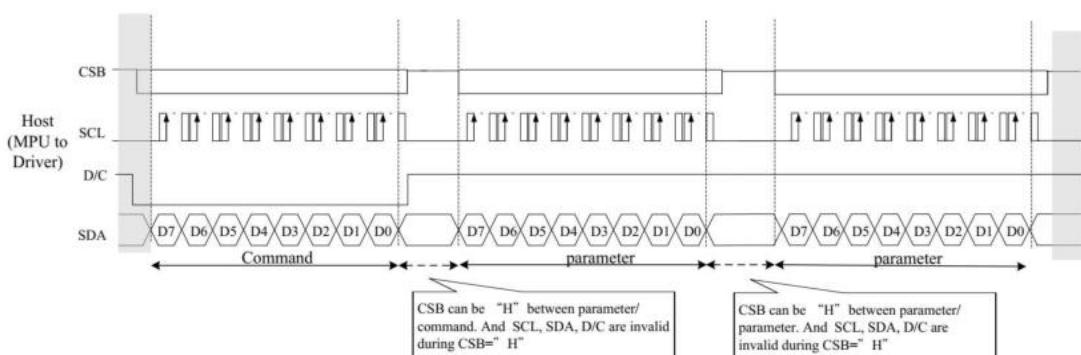
6.3.2 MCU Serial Interface (4-wire SPI)



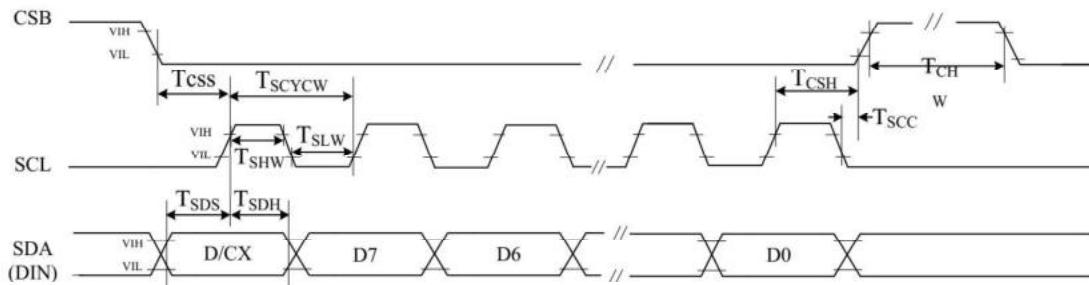
4 pin serial interface characteristics(write mode)



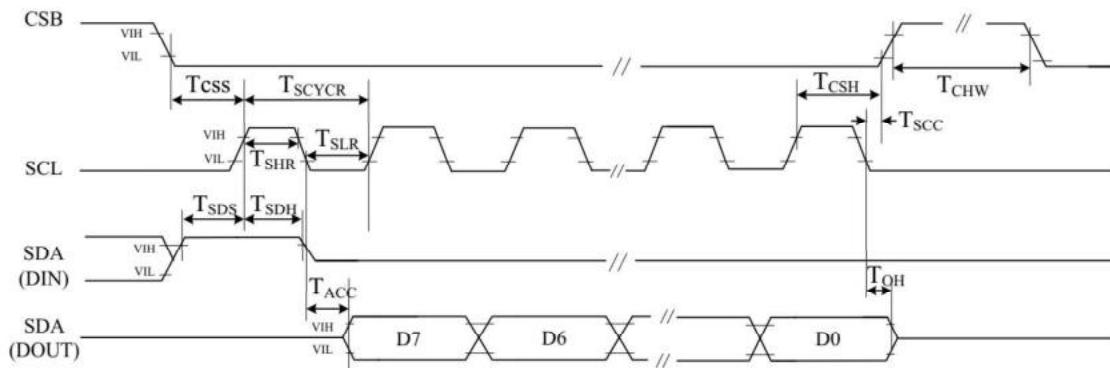
4 pin serial interface characteristics(read mode)



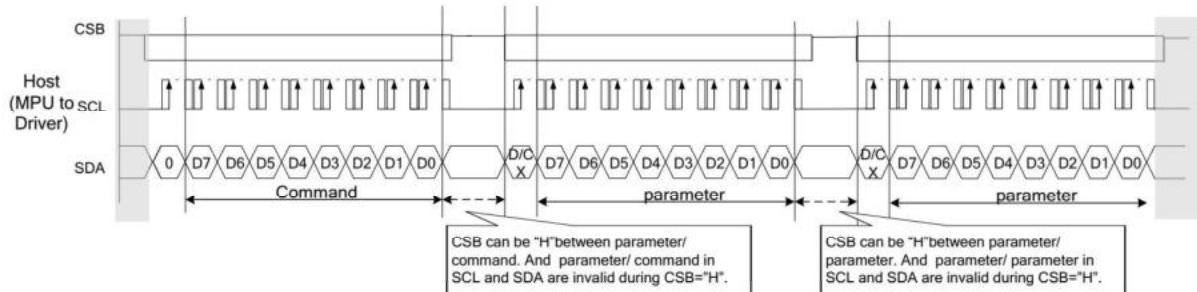
6.3.3 MCU Serial Interface (3-wire SPI)



3 pin serial interface characteristics (write mode)



3 pin serial interface characteristics (read mode)



Description	-The command defines as :		
	1 st parameter		
Bit	Name	Description	
0	RST_N	RST_N function 1: no effect. (default) 0: Booster OFF, Register data are set to their default values, and Source/Boder/Vcom: floating	
1	SHD_N	SHD_N function 0 : Booster OFF, register data are kept, and Source/Boder/Vcom are kept 0V or floating. 1 : Booster on. (default)	
2	SHL	SHL function 0: Shift left; First data=Sn→Sn-1 →...→S2→Last data=S1. 1: Shift right: First data=S1→S2 →...→Sn-1→Last data=Sn. (default)	
3	UD	UD function 0:Scan down; First line=Gn→Gn-1 →...→G2→Last line=G1. 1:Scan up; First line=G1→G2 →....→Gn-1→Last line=Gn. (default)	
5	PST_MODE	Power switch operation mode 0:Power switching time in the period of frame scanning.(default) 1:Power switching time in the external period before frame scanning.	
7-6	RES[1,0]	Resolution setting 00: Display resolution is 176x296 (default) 01: Display resolution is 128x296 10: Display resolution is 128x250 11: Display resolution is 112x204	
2 nd parameter			
Bit	Name	Description	
0	VC_LUTZ	VCOM status function 0 : No effect 1 : After refreshing display,the output of VCOM is set to floating automatically (default)	
1	NORG	VCOM status function 0 : No effect (default) 1 : After refreshing display, VCOM is tied to GND before power off	
2	TIEG	VGN power off status function 0 : No effect (default) 1 : Power off, VGN will be tied to GND	
3	TS_AUTO	Temperature sensing will be activated automatically one time 0 : Before enabling booster, Temperature Sensor will be activated automatically one time. 1 : When RST_N low to high, Temperature Sensor will be activated automatically one time. (default)	
4	VCMZ	VCOM status function 0 : No effect (default) 1 : VCOM is always floating	
5	FOPT	FOPT function 0: Scan 1 frame after waveform finished(default) 1: No scan after waveform finished and switch the source channel output to Hiz.	
7	LUT_EN	LUT selection setting 0 : Using LUT from MTP(default) 1 : Using LUT from register	

Priority of VCOM setting: VCMZ > NORG > FOPT > VC_LUTZ

FOPT setting is part of refreshing display.
 FOPT: Power off floating.

Notes:

1. Non-select gate line keep at VGN for DSP/DRF and AMV
2. Dummy source line follow LUTC for DSP/DRF
3. When SHD_N become low, DCDC will turn off. Register and SRAM data will keep until VDD turn off. SD output and VCOM will base on previous condition. It may have two condition:0V or floating.
4. When RST_N become low, driver will reset. All register will reset to default value. All of the driver's functions will disable. Source/Gate/Border/VCOM will be released to floating

R01H											Code
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PWR	W	0	0	0	0	0	0	0	0	1	01h
1 st Parameter	W	1	-	-	-	-	V_MODE	VSC_EN	VDS_EN	VDG_EN	07h
2 nd Parameter	W	1	-	-	-	-	-	-	VGPN [1]	VGPN [0]	00h
3 rd Parameter	W	1	-	VSPL_0 [6:0]							00h
4 th Parameter	W	1	-	VSP_1 [6:0]							00h
5 th Parameter	W	1	-	VSN_1 [6:0]							00h
6 th Parameter	W	1	-	VSPL_1 [6:0]							00h

NOTE: “-” Don't care, can be set to VDD or GND level

Description	-The command defines as :																	
	1 st Parameter:																	
	<table border="1"> <thead> <tr> <th>Bit</th><th>Name</th><th>Description</th></tr> </thead> <tbody> <tr> <td>0</td><td>VDG_EN</td><td>Gate power selection. 0 : External gate power from VGP/VGN pins. 1 : Internal DCDC function for generate VGP/VGN. (default)</td></tr> <tr> <td>1</td><td>VDS_EN</td><td>Source power selection. 0 : External source power from VSP/VSN pins. 1 : Internal regulator function for generate VSP/VSN (default)</td></tr> <tr> <td>2</td><td>VSC_EN</td><td>Source LV power selection. 0 : External source power from VSPL pins. 1 : Internal regulator function for generate VSPL (default)</td></tr> <tr> <td>3</td><td>V_MODE</td><td>Source Power switching mode. 0: Mode0(default) 1: Mode1</td></tr> </tbody> </table>			Bit	Name	Description	0	VDG_EN	Gate power selection. 0 : External gate power from VGP/VGN pins. 1 : Internal DCDC function for generate VGP/VGN. (default)	1	VDS_EN	Source power selection. 0 : External source power from VSP/VSN pins. 1 : Internal regulator function for generate VSP/VSN (default)	2	VSC_EN	Source LV power selection. 0 : External source power from VSPL pins. 1 : Internal regulator function for generate VSPL (default)	3	V_MODE	Source Power switching mode. 0: Mode0(default) 1: Mode1
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2	VSC_EN	Source LV power selection. 0 : External source power from VSPL pins. 1 : Internal regulator function for generate VSPL (default)																
3	V_MODE	Source Power switching mode. 0: Mode0(default) 1: Mode1																
	2nd Parameter:																	
	<table border="1"> <thead> <tr> <th>Bit</th><th>Name</th><th>Description</th></tr> </thead> <tbody> <tr> <td>1-0</td><td>VGPN</td><td>VGPN Voltage Level. 00: VGP=20 v, VGN=-20v (default) 01: VGP=17 v, VGN=-17v 10: VGP=15 v, VGN=-15v 11: VGP=10 v, VGN=-10v</td></tr> </tbody> </table>			Bit	Name	Description	1-0	VGPN	VGPN Voltage Level. 00: VGP=20 v, VGN=-20v (default) 01: VGP=17 v, VGN=-17v 10: VGP=15 v, VGN=-15v 11: VGP=10 v, VGN=-10v									
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1-0	VGPN	VGPN Voltage Level. 00: VGP=20 v, VGN=-20v (default) 01: VGP=17 v, VGN=-17v 10: VGP=15 v, VGN=-15v 11: VGP=10 v, VGN=-10v																

3rd & 4th & 6th Parameter: Internal VSP_1/VSPL_0/ VSPL_1 power selection

Bit	Name	Description					
		Internal VSP & VSPL power selection.					
		bit[6:0]	Voltage(V)	bit [6:0]	Voltage(V)	bit [6:0]	Voltage(V)
6-0	VSP_1 & VSPL_0 & VSPL_1	0000000	00h	3	0101001	29h	7.1
		0000001	01h	3.1	0101010	2Ah	7.2
		0000010	02h	3.2	0101011	2Bh	7.3
		0000011	03h	3.3	0101100	2Ch	7.4
		0000100	04h	3.4	0101101	2Dh	7.5
		0000101	05h	3.5	0101110	2Eh	7.6
		0000110	06h	3.6	0101111	2Fh	7.7
		0000111	07h	3.7	0110000	30h	7.8
		0001000	08h	3.8	0110001	31h	7.9
		0001001	09h	3.9	0110010	32h	8
		0001010	0Ah	4	0110011	33h	8.1
		0001011	0Bh	4.1	0110100	34h	8.2
		0001100	0Ch	4.2	0110101	35h	8.3
		0001101	0Dh	4.3	0110110	36h	8.4
		0001110	0Eh	4.4	0110111	37h	8.5
		0001111	0Fh	4.5	0111000	38h	8.6
		0010000	10h	4.6	0111001	39h	8.7
		0010001	11h	4.7	0111010	3Ah	8.8
		0010010	12h	4.8	0111011	3Bh	8.9
		0010011	13h	4.9	0111100	3Ch	9
		0010100	14h	5	0111101	3Dh	9.1
		0010101	15h	5.1	0111110	3Eh	9.2
		0010110	16h	5.2	0111111	3Fh	9.3
		0010111	17h	5.3	1000000	40h	9.4
		0011000	18h	5.4	1000001	41h	9.5
		0011001	19h	5.5	1000010	42h	9.6
		0011010	1Ah	5.6	1000011	43h	9.7
		0011011	1Bh	5.7	1000100	44h	9.8
		0011100	1Ch	5.8	1000101	45h	9.9
		0011101	1Dh	5.9	1000110	46h	10
		0011110	1Eh	6	1000111	47h	10.1
		0011111	1Fh	6.1	1001000	48h	10.2
		0100000	20h	6.2	1001001	49h	10.3
		0100001	21h	6.3	1001010	4Ah	10.4
		0100010	22h	6.4	1001011	4Bh	10.5
		0100011	23h	6.5	1001100	4Ch	10.6
		0100100	24h	6.6	1001101	4Dh	10.7
		0100101	25h	6.7	1001110	4Eh	10.8
		0100110	26h	6.8	1001111	4Fh	10.9
		0100111	27h	6.9	1010000	50h	11
		0101000	28h	7	1010001	51h	11.1

other 15

5th Parameter: Internal VSN_1 power selection

Bit	Name	Description					
		Internal VSN power selection.					
		bit[6:0]	Voltage(V)	bit [6:0]	Voltage(V)	bit [6:0]	Voltage(V)
6-0	VSN_1	0000000	00h	-3	0101001	29h	-7.1
		0000001	01h	-3.1	0101010	2Ah	-7.2
		0000010	02h	-3.2	0101011	2Bh	-7.3
		0000011	03h	-3.3	0101100	2Ch	-7.4
		0000100	04h	-3.4	0101101	2Dh	-7.5
		0000101	05h	-3.5	0101110	2Eh	-7.6
		0000110	06h	-3.6	0101111	2Fh	-7.7
		0000111	07h	-3.7	0110000	30h	-7.8
		0001000	08h	-3.8	0110001	31h	-7.9
		0001001	09h	-3.9	0110010	32h	-8
		0001010	0Ah	-4	0110011	33h	-8.1
		0001011	0Bh	-4.1	0110100	34h	-8.2
		0001100	0Ch	-4.2	0110101	35h	-8.3
		0001101	0Dh	-4.3	0110110	36h	-8.4
		0001110	0Eh	-4.4	0110111	37h	-8.5
		0001111	0Fh	-4.5	0111000	38h	-8.6
		0010000	10h	-4.6	0111001	39h	-8.7
		0010001	11h	-4.7	0111010	3Ah	-8.8
		0010010	12h	-4.8	0111011	3Bh	-8.9
		0010011	13h	-4.9	0111100	3Ch	-9
		0010100	14h	-5	0111101	3Dh	-9.1
		0010101	15h	-5.1	0111110	3Eh	-9.2
		0010110	16h	-5.2	0111111	3Fh	-9.3
		0010111	17h	-5.3	1000000	40h	-9.4
		0011000	18h	-5.4	1000001	41h	-9.5
		0011001	19h	-5.5	1000010	42h	-9.6
		0011010	1Ah	-5.6	1000011	43h	-9.7
		0011011	1Bh	-5.7	1000100	44h	-9.8
		0011100	1Ch	-5.8	1000101	45h	-9.9
		0011101	1Dh	-5.9	1000110	46h	-10
		0011110	1Eh	-6	1000111	47h	-10.1
		0011111	1Fh	-6.1	1001000	48h	-10.2
		0100000	20h	-6.2	1001001	49h	-10.3
		0100001	21h	-6.3	1001010	4Ah	-10.4
		0100010	22h	-6.4	1001011	4Bh	-10.5
		0100011	23h	-6.5	1001100	4Ch	-10.6
		0100100	24h	-6.6	1001101	4Dh	-10.7
		0100101	25h	-6.7	1001110	4Eh	-10.8
		0100110	26h	-6.8	1001111	4Fh	-10.9
		0100111	27h	-6.9	1010000	50h	-11
		0101000	28h	-7	1010001	51h	-7.1

5th Parameter: Internal VSN_1 power selection

Bit	Name	Description					
		Internal VSN power selection.					
		bit[6:0]	Voltage(V)	bit [6:0]	Voltage(V)	bit [6:0]	Voltage(V)
		0000000	00h	-3	0101001	29h	-7.1
		0000001	01h	-3.1	0101010	2Ah	-7.2
		0000010	02h	-3.2	0101011	2Bh	-7.3
		0000011	03h	-3.3	0101100	2Ch	-7.4
		0000100	04h	-3.4	0101101	2Dh	-7.5
		0000101	05h	-3.5	0101110	2Eh	-7.6
		0000110	06h	-3.6	0101111	2Fh	-7.7
		0000111	07h	-3.7	0110000	30h	-7.8
		0001000	08h	-3.8	0110001	31h	-7.9
		0001001	09h	-3.9	0110010	32h	-8
		0001010	0Ah	-4	0110011	33h	-8.1
		0001011	0Bh	-4.1	0110100	34h	-8.2
		0001100	0Ch	-4.2	0110101	35h	-8.3
		0001101	0Dh	-4.3	0110110	36h	-8.4
		0001110	0Eh	-4.4	0110111	37h	-8.5
		0001111	0Fh	-4.5	0111000	38h	-8.6
		0010000	10h	-4.6	0111001	39h	-8.7
		0010001	11h	-4.7	0111010	3Ah	-8.8
		0010010	12h	-4.8	0111011	3Bh	-8.9
		0010011	13h	-4.9	0111100	3Ch	-9
		0010100	14h	-5	0111101	3Dh	-9.1
		0010101	15h	-5.1	0111110	3Eh	-9.2
		0010110	16h	-5.2	0111111	3Fh	-9.3
		0010111	17h	-5.3	1000000	40h	-9.4
		0011000	18h	-5.4	1000001	41h	-9.5
		0011001	19h	-5.5	1000010	42h	-9.6
		0011010	1Ah	-5.6	1000011	43h	-9.7
		0011011	1Bh	-5.7	1000100	44h	-9.8
		0011100	1Ch	-5.8	1000101	45h	-9.9
		0011101	1Dh	-5.9	1000110	46h	-10
		0011110	1Eh	-6	1000111	47h	-10.1
		0011111	1Fh	-6.1	1001000	48h	-10.2
		0100000	20h	-6.2	1001001	49h	-10.3
		0100001	21h	-6.3	1001010	4Ah	-10.4
		0100010	22h	-6.4	1001011	4Bh	-10.5
		0100011	23h	-6.5	1001100	4Ch	-10.6
		0100100	24h	-6.6	1001101	4Dh	-10.7
		0100101	25h	-6.7	1001110	4Eh	-10.8
		0100110	26h	-6.8	1001111	4Fh	-10.9
		0100111	27h	-6.9	1010000	50h	-11
		0101000	28h	-7	1010001	51h	-7.1

other -15

	Notes:																																				
	1. VSP_0/VSN_0 voltage output is ±15 V fixed value. 2. When switching Mode0 or Mode1, the voltage output is: Mode0: VSP_0(+15) / VSN_0 (-15) / VSPL_0 (+3~+15) Mode1: VSP_1(+3 ~ +15) / VSN_1(-3 ~ -15) / VSPL_1(+3 ~ +15)																																				
	<table border="1"> <thead> <tr> <th></th> <th>Mode0</th> <th>Mode1</th> </tr> </thead> <tbody> <tr> <td>VSP</td> <td>VSP_0(+15)</td> <td>VSP_1(+3~+15)</td> </tr> <tr> <td>VSN</td> <td>VSN_0(-15)</td> <td>VSN_1(-3~-15)</td> </tr> <tr> <td>VSPL</td> <td>VSPL_0(+3~+15)</td> <td>VSPL_1(+3~+15)</td> </tr> </tbody> </table>			Mode0	Mode1	VSP	VSP_0(+15)	VSP_1(+3~+15)	VSN	VSN_0(-15)	VSN_1(-3~-15)	VSPL	VSPL_0(+3~+15)	VSPL_1(+3~+15)																							
	Mode0	Mode1																																			
VSP	VSP_0(+15)	VSP_1(+3~+15)																																			
VSN	VSN_0(-15)	VSN_1(-3~-15)																																			
VSPL	VSPL_0(+3~+15)	VSPL_1(+3~+15)																																			
	3. If gate voltage is set to +/-15v, +/-10v, IC will auto correct source voltage as follows I. VGP- VSP_0 / VSPL_0 / VSP_1 / VSPL_1 >= 2v II. VGN- VSN_0 / VSN_1 >= -2v For example:																																				
	<table border="1"> <thead> <tr> <th></th> <th>symbol</th> <th>Voltage setting</th> <th>Real Voltage</th> </tr> </thead> <tbody> <tr> <td rowspan="10">Voltage</td> <td>VGP</td> <td>10v</td> <td>+10v</td> </tr> <tr> <td>VGN</td> <td>10v</td> <td>-10v</td> </tr> <tr> <td>VSP_0</td> <td>+15v</td> <td>+8v</td> </tr> <tr> <td>VSN_0</td> <td>-15v</td> <td>-8v</td> </tr> <tr> <td>VSP_1</td> <td>+5v</td> <td>+5v</td> </tr> <tr> <td>VSN_1</td> <td>-5v</td> <td>-5v</td> </tr> <tr> <td>VSPL</td> <td>+15v</td> <td>+8v</td> </tr> <tr> <td>VCOMH</td> <td>+15v+(-2v)</td> <td>+8v+(-2v)</td> </tr> <tr> <td>VCOML</td> <td>-15v+(-2v)</td> <td>-8v+(-2v)</td> </tr> <tr> <td>VCOMDC</td> <td>-2v</td> <td>-2v</td> </tr> </tbody> </table>			symbol	Voltage setting	Real Voltage	Voltage	VGP	10v	+10v	VGN	10v	-10v	VSP_0	+15v	+8v	VSN_0	-15v	-8v	VSP_1	+5v	+5v	VSN_1	-5v	-5v	VSPL	+15v	+8v	VCOMH	+15v+(-2v)	+8v+(-2v)	VCOML	-15v+(-2v)	-8v+(-2v)	VCOMDC	-2v	-2v
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	VCOMDC	-2v	-2v																																		
	4. Voltage setting limit: VSP_0 ≥ VSPL_0 , VSP_1 ≥ VSPL_1																																				
Restriction																																					

R02H											
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
POF	W	0	0	0	0	0	0	0	1	0	02H
1 st Parameter	W	0	-	-	-	-	-	-	-	EDSE	00

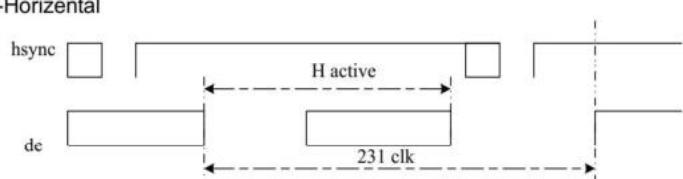
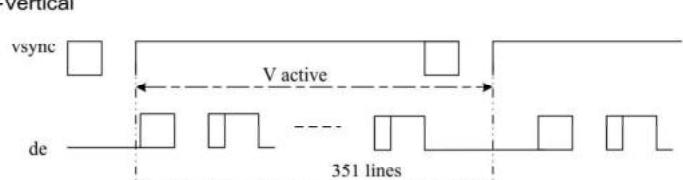
NOTE: “-” Don't care, can be set to VDD or GND level

Description	<p>-The command defines as :</p> <ul style="list-style-type: none"> After power off command, driver will power off base on power off sequence. After power off command, BUSY_N signal will drop from high to low. When finish the power off sequence, BUSY_N singal will rise from low to high. Power off command will turn off charge pump, T-con, source driver, gate driver, VCOM, temperature sensor, but register and SRAM data will keep until VDD off. SD output and VCOM will base on previous condition. It may have two conditions: 0v or floating. <p>1st parameter</p> <table border="1"> <thead> <tr> <th>Bit</th><th>Name</th><th>Description</th></tr> </thead> <tbody> <tr> <td>0</td><td>EDSE</td><td>EPD Discharge Trigger 0 : Disable EPD discharge (default) 1 : Enable EPD discharge</td></tr> </tbody> </table>		Bit	Name	Description	0	EDSE	EPD Discharge Trigger 0 : Disable EPD discharge (default) 1 : Enable EPD discharge			
Bit	Name	Description									
0	EDSE	EPD Discharge Trigger 0 : Disable EPD discharge (default) 1 : Enable EPD discharge									
Restriction	This command only active when BUSY_N = "1".										

R03H											
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PFS	W	0	0	0	0	0	0	0	1	1	03H
1 st Parameter	W	1	-		T_VDPG_OFF [1:0]		-		T_VDS_OFF [1:0]		00h
2 nd Parameter	W	1		VGP_LEN[3:0]				VGP_EXT[3:0]			54h
3 rd Parameter	W	1		XON_DLY[3:0]				XON_LEN[3:0]			44h

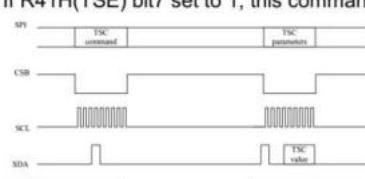
NOTE: “-” Don't care, can be set to VDD or GND level

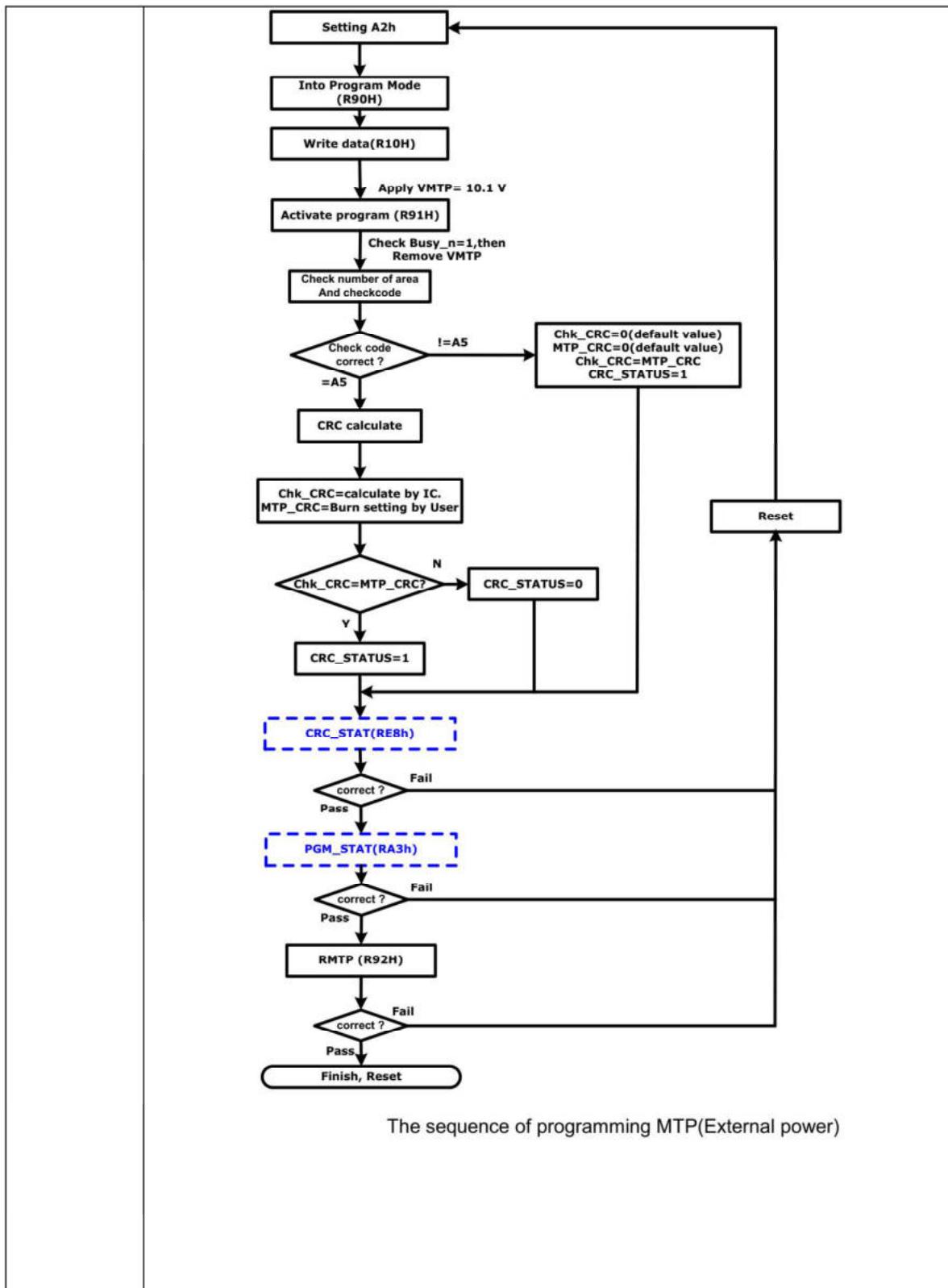
Description	<p>-The command defines as :</p> <p>1st Parameter:</p> <table border="1"> <thead> <tr> <th>Bit</th><th>Name</th><th>Description</th></tr> </thead> <tbody> <tr> <td>1-0</td><td>T_VDS_OFF</td><td> Power off sequence of VSP /VSN 00: 20 ms (default) 01: 40 ms 10: 60 ms 11: 80 ms </td></tr> <tr> <td>5-4</td><td>T_VDPG_OFF</td><td> Power off sequence of VGP and VGN 00: 20 ms (default) 01: 40 ms 10: 60 ms 11: 80 ms </td></tr> </tbody> </table> <p>2nd Parameter</p> <table border="1"> <thead> <tr> <th>Bit</th><th>Name</th><th>Description</th></tr> </thead> <tbody> <tr> <td>1-0</td><td>VGP_EXT</td><td> VGP extension time 0000: 0 ms 0001: 500 ms 0010: 1000 ms 0011: 1500 ms 0100: 2000 ms (default) 0101: 2500 ms 0110: 3000 ms 0111: 3500 ms 1000: 4000 ms 1001: 4500 ms 1010: 5000 ms 1011: 5500 ms 1100: 6000 ms 1101: 6500 ms </td></tr> <tr> <td>7-4</td><td>VGP_LEN</td><td> When power off, the length of time VGP stay 10V 0000: 0 ms 0001: 500 ms 0010: 1000 ms 0011: 1500 ms 0100: 2000 ms 0101: 2500 ms (default) 0110: 3000 ms 0111: 3500 ms 1000: 4000 ms 1001: 4500 ms 1010: 5000 ms 1011: 5500 ms </td></tr> </tbody> </table>	Bit	Name	Description	1-0	T_VDS_OFF	Power off sequence of VSP /VSN 00: 20 ms (default) 01: 40 ms 10: 60 ms 11: 80 ms	5-4	T_VDPG_OFF	Power off sequence of VGP and VGN 00: 20 ms (default) 01: 40 ms 10: 60 ms 11: 80 ms	Bit	Name	Description	1-0	VGP_EXT	VGP extension time 0000: 0 ms 0001: 500 ms 0010: 1000 ms 0011: 1500 ms 0100: 2000 ms (default) 0101: 2500 ms 0110: 3000 ms 0111: 3500 ms 1000: 4000 ms 1001: 4500 ms 1010: 5000 ms 1011: 5500 ms 1100: 6000 ms 1101: 6500 ms	7-4	VGP_LEN	When power off, the length of time VGP stay 10V 0000: 0 ms 0001: 500 ms 0010: 1000 ms 0011: 1500 ms 0100: 2000 ms 0101: 2500 ms (default) 0110: 3000 ms 0111: 3500 ms 1000: 4000 ms 1001: 4500 ms 1010: 5000 ms 1011: 5500 ms
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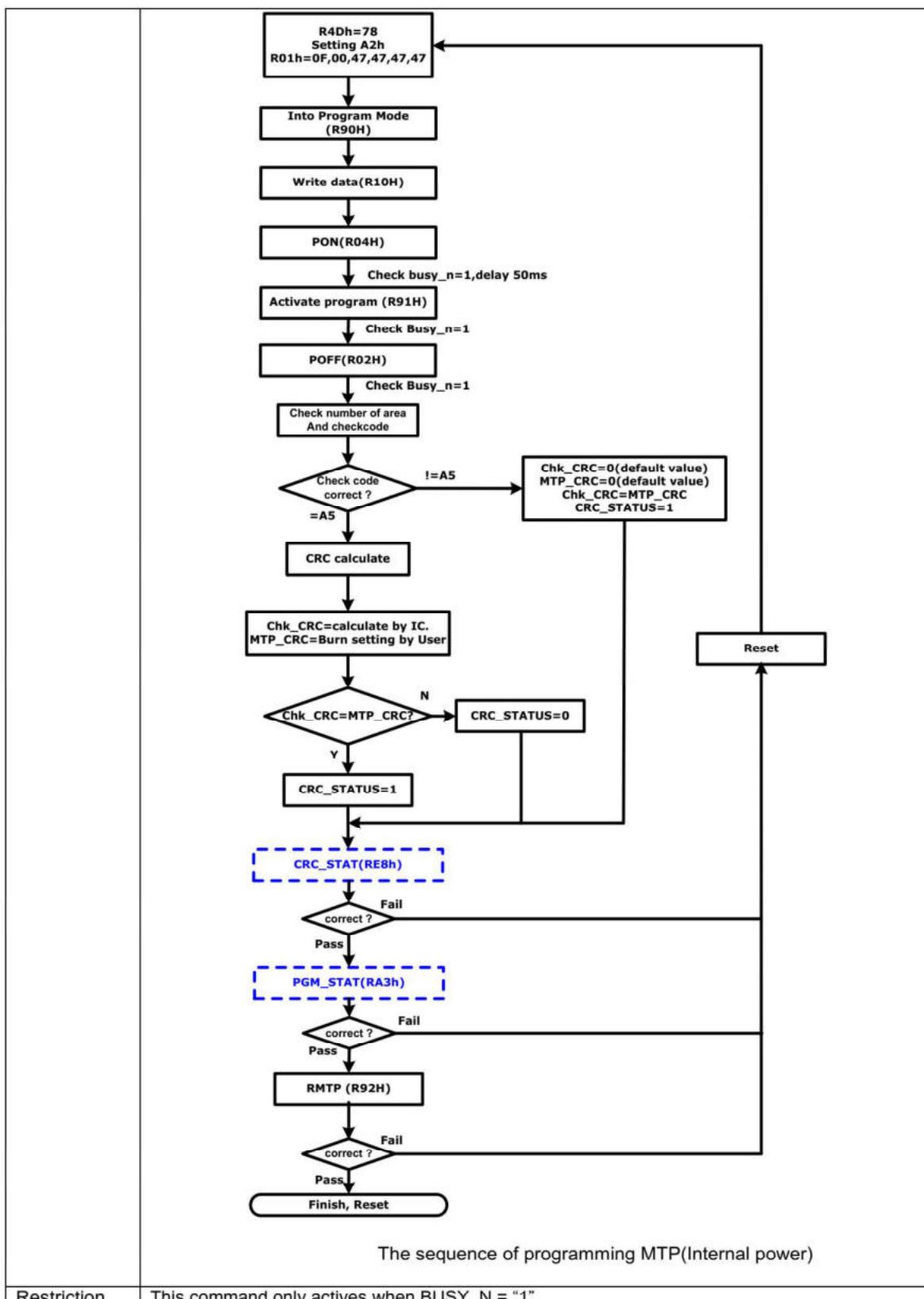
Description	<p>-The command defines as:</p> <p>The command controls the PLL clock frequency. The PLL structure must support the following frame rates:</p> <table border="1"> <tr><td>bit3</td><td>Dynamic frame rate</td></tr> <tr><td>0</td><td>Disable(default)</td></tr> <tr><td>1</td><td>Enable</td></tr> </table> <table border="1"> <tr><td>FR[2:0]</td><td>Frame rate</td></tr> <tr><td>000</td><td>12.5 Hz</td></tr> <tr><td>001</td><td>25 Hz</td></tr> <tr><td>010</td><td>50 Hz(default)</td></tr> <tr><td>011</td><td>65 Hz</td></tr> <tr><td>100</td><td>75 Hz</td></tr> <tr><td>101</td><td>85 Hz</td></tr> <tr><td>110</td><td>100 Hz</td></tr> <tr><td>111</td><td>120 Hz</td></tr> </table>	bit3	Dynamic frame rate	0	Disable(default)	1	Enable	FR[2:0]	Frame rate	000	12.5 Hz	001	25 Hz	010	50 Hz(default)	011	65 Hz	100	75 Hz	101	85 Hz	110	100 Hz	111	120 Hz
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101	85 Hz																								
110	100 Hz																								
111	120 Hz																								
remark	<p>-Horizontal</p>  <p>-Vertical</p> 																								
Restriction																									

R40H	Bit											
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code	
TSC	W	0	0	1	0	0	0	0	0	0	40H	
1 st Parameter	R	1	D10/TS[7]	D9/TS[6]	D8/TS[5]	D7/TS[4]	D6/TS[3]	D5/TS[2]	D4/TS[1]	D3/TS[0]	-	
2 nd Parameter	R	1	D2/ TS[9]	D1/ TS[8]	D0	-	-	-	-	-	-	

NOTE: “-” Don't care, can be set to VDD or GND level

Description	<p>-The command define as follows:</p> <p>This command indicates the temperature value.</p> <p>If R41H(TSE) bit7 set to 0, this command reads internal temperature sensor value. If R41H(TSE) bit7 set to 1, this command reads external (LM75) temperature sensor value</p>  <table border="1"> <tr><td>TS[7:0]/D[10:3]</td><td>T (°C)</td><td>TS[7:0]/D[10:3]</td><td>T (°C)</td><td>TS[7:0]/D[10:3]</td><td>T (°C)</td></tr> <tr><td>11100111</td><td>-25</td><td>0000000</td><td>0</td><td>00011001</td><td>25</td></tr> <tr><td>11101000</td><td>-24</td><td>00000001</td><td>1</td><td>00011010</td><td>26</td></tr> <tr><td>11101001</td><td>-23</td><td>00000010</td><td>2</td><td>00011011</td><td>27</td></tr> <tr><td>11101010</td><td>-22</td><td>00000011</td><td>3</td><td>00011100</td><td>28</td></tr> <tr><td>11101011</td><td>-21</td><td>00000100</td><td>4</td><td>00011101</td><td>29</td></tr> <tr><td>11101100</td><td>-20</td><td>00000101</td><td>5</td><td>00011110</td><td>30</td></tr> <tr><td>11101101</td><td>-19</td><td>00000110</td><td>6</td><td>00011111</td><td>31</td></tr> <tr><td>11101110</td><td>-18</td><td>00000111</td><td>7</td><td>00100000</td><td>32</td></tr> <tr><td>11101111</td><td>-17</td><td>00001000</td><td>8</td><td>00100001</td><td>33</td></tr> <tr><td>11110000</td><td>-16</td><td>00001001</td><td>9</td><td>00100010</td><td>34</td></tr> </table>	TS[7:0]/D[10:3]	T (°C)	TS[7:0]/D[10:3]	T (°C)	TS[7:0]/D[10:3]	T (°C)	11100111	-25	0000000	0	00011001	25	11101000	-24	00000001	1	00011010	26	11101001	-23	00000010	2	00011011	27	11101010	-22	00000011	3	00011100	28	11101011	-21	00000100	4	00011101	29	11101100	-20	00000101	5	00011110	30	11101101	-19	00000110	6	00011111	31	11101110	-18	00000111	7	00100000	32	11101111	-17	00001000	8	00100001	33	11110000	-16	00001001	9	00100010	34
TS[7:0]/D[10:3]	T (°C)	TS[7:0]/D[10:3]	T (°C)	TS[7:0]/D[10:3]	T (°C)																																																														
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11101000	-24	00000001	1	00011010	26																																																														
11101001	-23	00000010	2	00011011	27																																																														
11101010	-22	00000011	3	00011100	28																																																														
11101011	-21	00000100	4	00011101	29																																																														
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11101111	-17	00001000	8	00100001	33																																																														
11110000	-16	00001001	9	00100010	34																																																														





Restriction	This command only actives when BUSY_N = "1".										
-------------	--	--	--	--	--	--	--	--	--	--	--

R9EH	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
REV2	W	0	1	0	0	1	1	1	1	0	9EH
1 st Parameter	R	1	0	0	0	0	0	0	0	1	01h

RE4H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
LVSEL	W	0	1	1	1	0	0	1	0	0	E4H
1 st Parameter	W	1	-	-	-	-	-	-	LVD_SEL[1:0]	03h	

NOTE: “-” Don’t care, can be set to VDD or GND level

Description	LVD_SEL[1:0]: Low Power Voltage Selection	
	LVD_SEL[1:0]	LVD value
	00	< 2.2 V
	01	< 2.3 V
	10	< 2.4 V
	11	< 2.5 V (default)
Restriction		

8. Handling, Safety and Environment Requirements

Warning

The display glass may break when it is dropped or bumped on a hard surface. Handle with care. Should the display break, do not touch the electrophoretic material. In case of contact with electrophoretic material, wash with water and soap.

Caution

The display module should not be exposed to harmful gases, such as acid and alkali gases, which corrode electronic components. Disassembling the display module.

Disassembling the display module can cause permanent damage and invalidates the warranty agreements.

Observe general precautions that are common to handling delicate electronic components. The glass can break and front surfaces can easily be damaged. Moreover the display is sensitive to static electricity and other rough environmental conditions.

Data sheet status

Product specification	This data sheet contains final product specifications.
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Limiting values

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

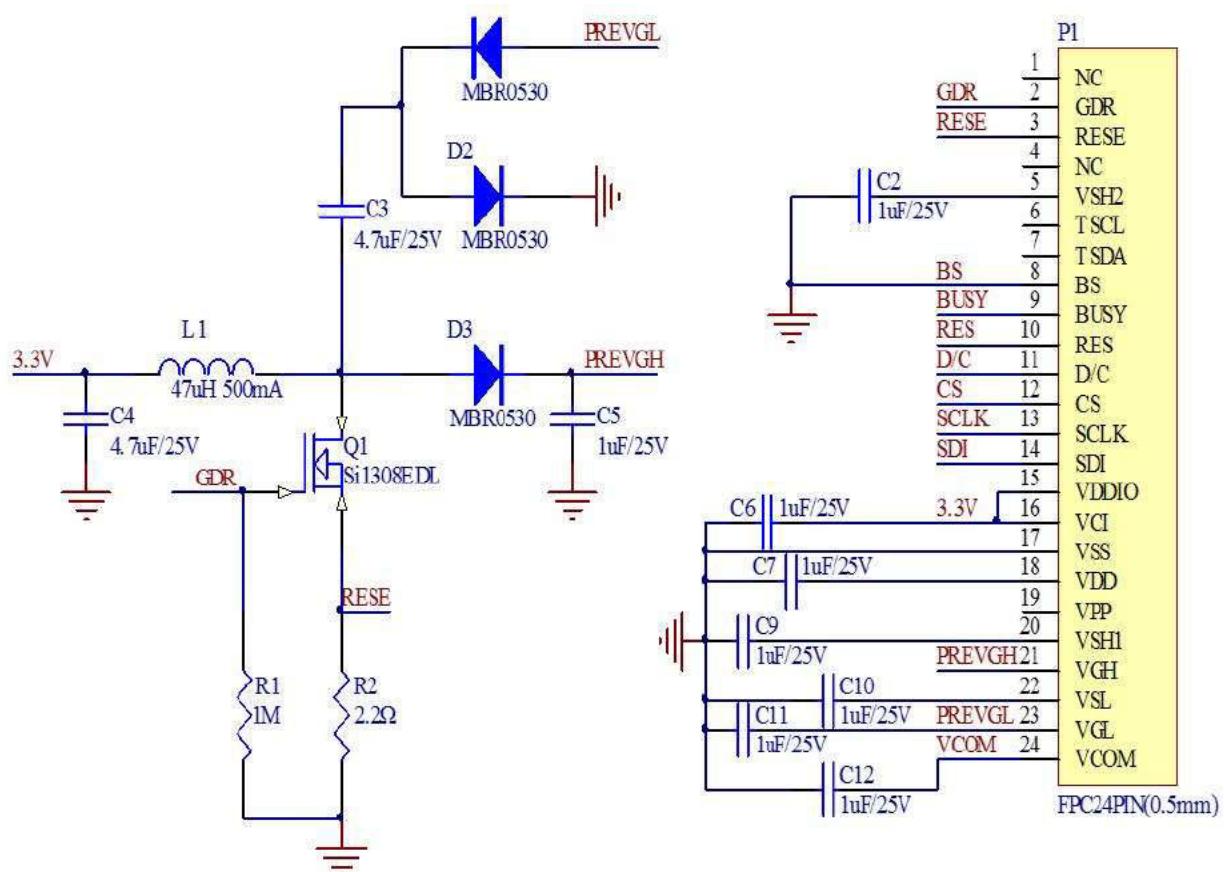
Where application information is given, it is advisory and does not form part of the specification.

9. Reliability test

NO	Test items	Test condition
1	Low-Temperature Storage	T = -25°C, 240 h Test in white pattern
2	High-Temperature Storage	T=60° C, RH=35%, 240h Test in white pattern
3	High-Temperature Operation	T=40° C, RH=35%, 240h
4	Low-Temperature Operation	0° C, 240h
5	High-Temperature, High-Humidity Operation	T=40° C, RH=80%, 240h
6	High Temperature, High Humidity Storage	T=50° C, RH=90%, 240h Test in white pattern
7	Temperature Cycle	1 cycle:[-25 °C 30min]→[+60 °C 30 min] : 50 cycles Test in white pattern
8	UV exposure Resistance	765W/m ² for 168hrs,40 °C Test in white pattern
9	ESD Gun	Air+/-15KV;Contact+/-8KV (Test finished product shell, not display only) Air+/-8KV;Contact+/-6KV (Naked EPD display, no including IC and FPC area) Air+/-4KV;Contact+/-2KV (Naked EPD display, including IC and FPC area)

Note: Put in normal temperature for 1hour after test finished, display performance is ok.

10. Typical Application Circuit



Part Name	Requirements for spare part
C1—C12	0603/0805; X5R/X7R; Voltage Rating: $\geq 25V$
R1、R2	0603/0805; 1% variation, $\geq 0.05W$
D1—D3	MBR0530: 1) Reverse DC Voltage $\geq 30V$ 2) $I_o \geq 500mA$ 3) Forward voltage $\leq 430mV$
Q1	Si1308EDL: 1) Drain-Source breakdown voltage $\geq 30V$ 2) $V_{gs(th)} \leq 1.5V$ 3) $R_{ds(on)} \leq 400m\Omega$
L1	refer to NR3015: $I_o = 500mA(\max)$
P1	24pins, 0.5mm pitch

11. Matched Development Kit

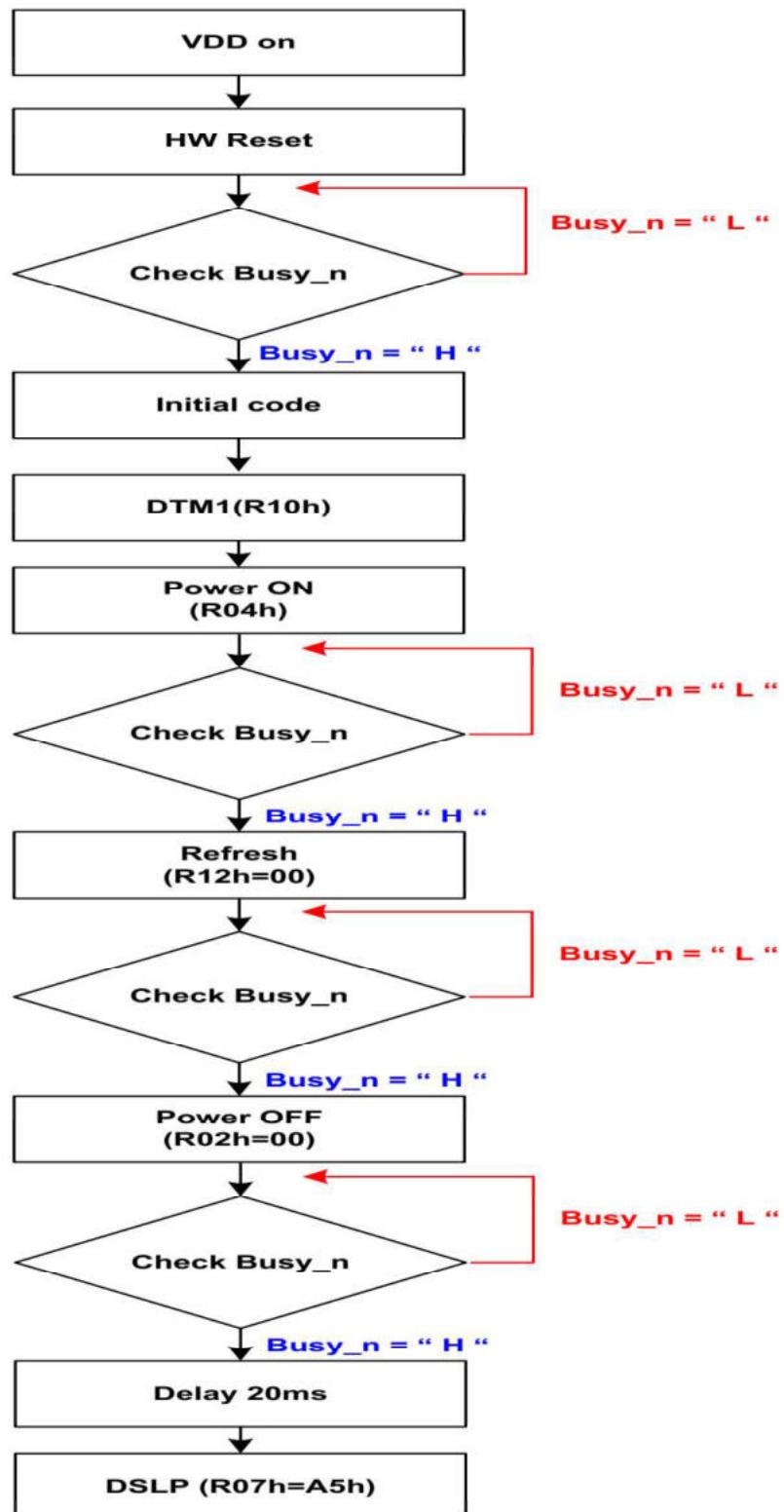
Our Development Kit designed for SPI E-paper Display aims to help users to learn how to use E-paper Display more easily. It can refresh blackwhite E-paper Display, three-color (black, white and red/Yellow) E-paper Display and four-color(black, white, red and yellow) WINSTAR Display 's E-paper Display. And it is also added the functions of USB serial port, FLASH chip, font chip, current detection ect.

Development Kit consists of the development board and the pinboard.

Supported development platforms include STM32, ESP32, ESP8266, Arduino UNO, etc.

12. Typical Operating Sequence

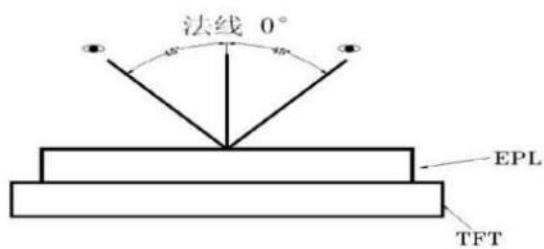
12.1 Normal Operation Flow



13. Inspection method and condition

13. 1 Inspection condition

Item	Condition
Illuminance	800~1500 lux
Temperature	22°C ±3°C
Humidity	55±10 %RH
Distance	≥30cm
Angle	Vertical fore and aft 45
Inspection method	By eyes

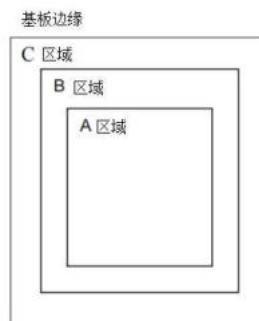


13.2 Zone definition

A Zone: Active area

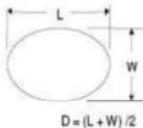
B Zone: Border zone

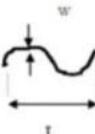
C Zone: From B zone edge to panel edge

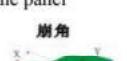
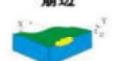
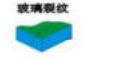


13. 3 General inspection standards for products

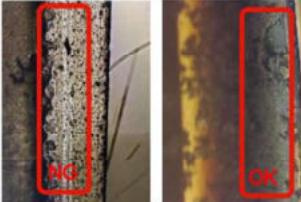
13.3.1 Appearance inspection standard

Inspection item		Figure		A zone inspection standard	B/C zone	Inspection method	MAJ/MIN	
Spot defects	Spot defects such as dot, foreign matter, air bubble, and dent etc.	Diameter $D=(L+W)/2$ (L-length, W-width) Measuring method shown in the figure below 	The distance between the two spots should not be less than 10mm	<p>7.5"-13.3"Module (Not include 7.5") : $D > 1\text{mm}$ N=0 $0.5 < D \leq 0.8$ $N \leq 4$ $D \leq 0.5$ Ignore $0.8 < D \leq 1$ N≤2</p> <p>4.2"-7.5"Module (Not include 4.2") : $D > 0.5$ N=0 $0.4 < D \leq 0.5$ $N \leq 2$ $D \leq 0.25$ Ignore $0.25 < D \leq 0.4$ N≤4</p> <p>Module below 4.2": $D > 0.5$ N=0 $0.4 < D \leq 0.5$ $N \leq 1$ $D \leq 0.25$ Ignore $0.25 < D \leq 0.4$ $N \leq 4$ $0.1\text{mm} < D \leq 0.25$ N≤3/cm²</p>		Foreign matter D≤1mm Pass	Check by eyes Film gauge	MIN

Inspection item		Figure		A zone inspection standard	B/C zone	Inspection method	MAJ/MIN
Line defects	Line defects such as scratch, hair etc.	L-Length, W-Width, $(W/L) < 1/4$ Judged by line, $(W/L) \geq 1/4$ Judged by dot 	The distance between the two lines should not be less than 5mm	<p>7.5"-13.3"Module (Not include 7.5") : $L > 10\text{mm}, N=0$ $W > 0.8\text{mm}, N=0$ $5\text{mm} \leq L \leq 10\text{mm}, 0.5\text{mm} \leq W \leq 0.8\text{mm}$ $N \leq 2$ $L \leq 5\text{mm}, W \leq 0.5\text{mm}$ Ignore</p> <p>4.2"-7.5"Module (Not include 4.2") : $L > 8\text{mm}, N=0$ $W > 0.2\text{mm}, N=0$ $2\text{mm} \leq L \leq 8\text{mm}, 0.1\text{mm} \leq W \leq 0.2\text{mm}$ N≤4 $L \leq 2\text{mm}, W \leq 0.1\text{mm}$ Ignore</p> <p>Module below 4.2": $L > 5\text{mm}, N=0$ $W > 0.2\text{mm}, N=0$ $2\text{mm} \leq L \leq 5\text{mm}, 0.1\text{mm} \leq W \leq 0.2\text{mm}$ N≤4 $L \leq 2\text{mm}, W \leq 0.1\text{mm}$ Ignore</p>	Ignore	Check by eyes Film gauge	MIN

Inspection item		Figure	Inspection standard	Inspection method	MAJ/MIN
Panel chipping and crack defects	TFT panel chipping	X the length, Y the width, Z the chipping height, T the thickness of the panel  	<p>Chipping at the edge: Module over 7.5" (Include 7.5") : $X \leq 6\text{mm}, Y \leq 1\text{mm}$ $Z \leq T$ N=3 Allowed</p> <p>Module below 7.5"(Not include 7.5"): $X \leq 3\text{mm}, Y \leq 1\text{mm}$ $Z \leq T$ N=3 Allowed</p> <p>Chipping on the corner: IC side $X \leq 2\text{mm}$ $Y \leq 2\text{mm}$, Non-IC side $X \leq 1\text{mm}$ $Y \leq 1\text{mm}$. Allowed</p> <p>Note: Chipping should not damage the edge wiring. If it does not affect the display, allowed</p>	Check by eyes Film gauge	MIN
	Crack		Crack at any zone of glass . Not allowed	Check by eyes Film gauge	MIN
	Burr edge		No exceed the positive and negative deviation of the outline dimensions $X+Y \leq 0.2\text{mm}$ Allowed	Calliper	MIN
	Curl of panel		Curl height $H \leq$ Total panel length 1% Allowed	Check by eyes	MIN

Inspection item		Figure	Inspection standard	Inspection method	MAJ / MIN
PS defect	Water proof film		1. Waterproof film damage, wrinkled, open edge, not allowed 2. Exceeding the edge of module(according to the lamination drawing) Not allowed 3. Edge warped exceeds height of technical file, not allowed	Check by eyes	MIN
RTV defect	Adhesive effect		Adhesive height exceeds the display surface, not allowed	Check by eyes	MIN
			1. Overflow, exceeds the panel side edge, affecting the size, not allowed 2. No adhesive at panel edge $\leq 1\text{mm}$, no exposure of wiring, allowed 3. No adhesive at edge and corner $1*1\text{mm}$, no exposure of wiring, allowed		
			Protection adhesive, coverage width within $W \leq 1.5\text{mm}$, no break of adhesive, allowed		
	Adhesive re-fill		Dispensing is uniform, without obvious concave and breaking, bubbling and swell, not higher than the upper surface of the PS, and the diameter of the adhesive re-filling is not more than 8mm, allowed	Check by eyes	MIN
EC defect	Adhesive bubble		1. Effective edge sealing area of hot melt products $\geq 1/2$ edge sealing area; 2. Bubble $a+b \geq 1/2$ effective width, $N \leq 3$, spacing $\geq 5\text{mm}$, allowed No exposure of wiring, allowed	Check by eyes	MIN

Inspection item		Figure	Inspection standard	Inspection method	MAJ/ MIN
EC defect	Adhesive effect		1. Overflow, exceeds the panel side edge, affecting the size, not allowed 2. No adhesive at panel edge $\leq 1\text{mm}$, no exposure of wiring, allowed 3. No adhesive at edge and corner $1*1\text{mm}$, no exposure of wiring, allowed 4. Adhesive height exceeds the display surface, not allowed	Visual, caliper	MIN
Silver dot adhesive defect	Silver dot adhesive		1. Single silver dot dispensing amount $\geq 1\text{mm}$, allowed 2. One of the double silver dot dispensing amount is $\geq 1\text{mm}$ and the other has adhesive (no reference to 1mm) Allowed	Visual	MIN
			Silver dot dispensing residue on the panel $\leq 0.2\text{mm}$, allowed	Film gauge	MIN
FPC defect	FPC wiring		FPC, TCP damage / gold finger peroxidation, adhesive residue, not allowed	Visual	MIJ
	FPC golden finger		The height of burr edge of TCP punching surface $\geq 0.4\text{mm}$, not allowed	Caliper	MIN
	FPC damage/cr ease		Damage and breaking, not allowed Crease does not affect the electrical performance display, allowed	Check by eyes	MIN

Inspection item		Figure	Inspection standard	Inspection method	MAJ/MIN
Protective film defect	Protective film	Scratch and crease on the surface but no affect to protection function, allowed		Check by eyes	MIN
		Adhesive at edge L≤5mm, W≤0.5mm, N=2, no entering into viewing area		Check by eyes	MIN
Stain defect	Stain	If stain can be normally wiped clean by > 99% alcohol, allowed		Visual	MIN
Pull tab defect	Pull tab	The position and direction meet the document requirements, and ensure that the protective film can be pulled off.		Check by eyes/ Manual pulling	MIN
Shading tape defect	Shading tape	Tilt≤10°, flat without warping, completely covering the IC.		Check by eyes/ Film gauge	MIN
Stiffener	Stiffener	Flat without warping. Exceeding the left and right edges of the FPC is not allowed. Left and right can be less than 0.5mm from FPC edge		Check by eyes	MIN
Label	Label/ Spraying code	The content meets the requirements of the work sheet. The attaching position meets the requirements of the technical documents.		Check by eyes	MIN

14. Packaging

TBD

15. Precautions

- (1) Do not apply pressure to the EPD panel in order to prevent damaging it.
- (2) Do not connect or disconnect the interface connector while the EPD panel is in operation.
- (3) Do not touch IC bonding area. It may scratch TFT lead or damage IC function.
- (4) Please be mindful of moisture to avoid its penetration into the EPD panel, which may cause damage during operation.
- (5) If the EPD Panel / Module is not refreshed every 24 hours, a phenomena known as "Ghosting" or "Image Sticking" may occur. It is recommended to refreshed the ESL /EPD Tag every 24 hours in use case. It is recommended that customer ships or stores the ESL / EPD Tag with a completely white image to avoid this issue
- (6) High temperature, high humidity, sunlight or fluorescent light may degrade the EPD panel's performance. Please do not expose the unprotected EPD panel to high temperature, high humidity, sunlight, or fluorescent for long periods of time.